

### GENERAL DESCRIPTION

The SGM41563 is a linear charger for single-cell Li+/polymer battery plus an ultra-low standby current boost operation for generating a 5V output from the battery power. Its wide input range allows charging with loose regulated power like conducting coil, solar cells or thermal coupling piles. The boost quiescent current (0.68μA TYP) is affordable even for small cell always-on standby application.

The SGM41563 is available in a Green SOIC-8 (Exposed Pad) package.

### FEATURES

- **Five Charge Voltage Options:**  
4.2V/4.25V/4.3V/4.35V/4.4V
- **5mA to 700mA Charger for Single-Cell Li+/Polymer Battery**
- **Constant-Current/Constant-Voltage Charging**
- **Die Temperature Charge Current Regulation**
- **-4% Voltage Fold-Back Power Retaining**
- **+2% Path Resistive Loss Compensation**
- **Floating Charge Over-Time Termination**
- **Ultra-Low Quiescent Current**
- **Programmable Charge Current**
- **Power-Saving Charging Indication**
- **Internal Over-Temperature Protection**
- **Available in a Green SOIC-8 (Exposed Pad) Package**

### APPLICATIONS

Rechargeable Battery Powered IoT Gadget  
Self-Powered IoT Terminals

### TYPICAL APPLICATION

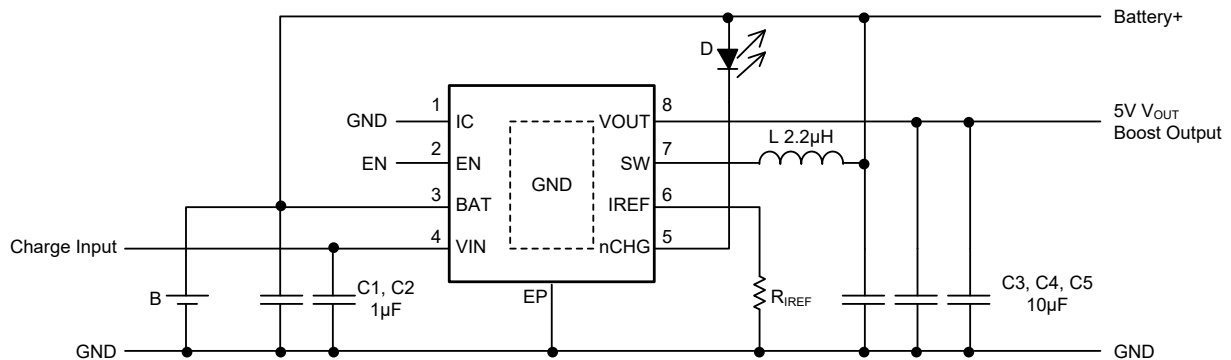


Figure 1. Typical Application Circuit

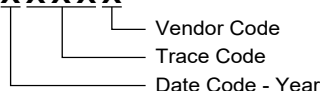
**PACKAGE/ORDERING INFORMATION**

MODEL	V <sub>CH</sub> (V)	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
SGM41563	4.2	SOIC-8 (Exposed Pad)	-40°C to +85°C	SGM41563-420YPS8G/TR	SGM CK9YPS8 XXXXX	Tape and Reel, 4000
	4.25	SOIC-8 (Exposed Pad)	-40°C to +85°C	SGM41563-425YPS8G/TR	SGM CKAYPS8 XXXXX	Tape and Reel, 4000
	4.3	SOIC-8 (Exposed Pad)	-40°C to +85°C	SGM41563-430YPS8G/TR	SGM CKBYPS8 XXXXX	Tape and Reel, 4000
	4.35	SOIC-8 (Exposed Pad)	-40°C to +85°C	SGM41563-435YPS8G/TR	SGM CKCYPS8 XXXXX	Tape and Reel, 4000
	4.4	SOIC-8 (Exposed Pad)	-40°C to +85°C	SGM41563-440YPS8G/TR	SGM CKDYPS8 XXXXX	Tape and Reel, 4000

**MARKING INFORMATION**

NOTE: XXXXX = Date Code, Trace Code and Vendor Code.

**XXXXX**



Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

**ABSOLUTE MAXIMUM RATINGS**

**Voltage Range**

- VIN to GND ..... -0.3V to 10V
- EN, SW, VOUT, IREF to GND ..... -0.3V to 6V
- BAT to GND ..... -0.3V to 5.5V
- nCHG to GND ..... -0.3V to 13.2V

**Package Thermal Resistance**

- SOIC-8 (Exposed Pad), θ<sub>JA</sub> ..... 42°C/W
- Junction Temperature ..... +150°C
- Storage Temperature Range ..... -65°C to +150°C
- Lead Temperature (Soldering, 10s) ..... +260°C

**ESD Susceptibility**

- HBM ..... 4000V
- CDM ..... 1000V

**RECOMMENDED OPERATING CONDITIONS**

- Supply Voltage Range ..... 2.7V to 7.5V
- Operating Junction Temperature Range ..... -40°C to +125°C
- Operating Ambient Temperature Ranges ..... -40°C to +85°C

**OVERSTRESS CAUTION**

Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.

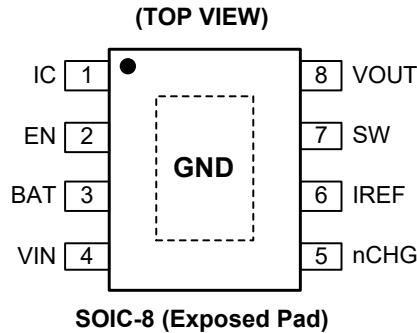
**ESD SENSITIVITY CAUTION**

This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

**DISCLAIMER**

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

**PIN CONFIGURATION**



**PIN DESCRIPTION**

PIN	NAME	TYPE	FUNCTION
1	IC	IC	Internal Connection. Connect this pin to ground.
2	EN	I	Boost Enable Input. This is a logic input pin to disable or enable the boost converter. Drive to logic low to disable the boost. Drive to logic high to enable the boost. Do not leave it floating.
3	BAT	IO	Battery. Output to the battery and/or system load, for charging and/or powering the system. The boost circuit is internally connected to this node as its bias.
4	VIN	P	Power Input. For powering this device and feeding to the BAT output.
5	nCHG	O	Charging Indication. This pin blinks during charging and keeps on for about 52s when the end-of-charge (EOC) condition is qualified.
6	IREF	IO	Maximum Charge Current Programming and Charge Disable Input. Drive to logic high to disable the charger. Connect a resistor between this pin and GND to set the charge current limit determined by the following equations: $I_{CHG} < 400\text{mA}, I_{CHG} (\text{mA}) = 24000/R_{IREF} (\text{k}\Omega);$ $I_{CHG} > 400\text{mA}, I_{CHG} (\text{mA}) = 20500/R_{IREF} (\text{k}\Omega) + 58\text{mA}.$
7	SW	IO	Chopping Output of the Boost. It is connected to the power inductor.
8	VOUT	O	Boost Converter Output. Place storage capacitor(s) close to this pin and clip between this pin and ground.
Exposed Pad	GND	G	Ground of the Circuit.

NOTE: I: Input, O: Output, IO: Input or Output, G: Ground, P: Power for the Circuit, IC: Internal Connection.

## ELECTRICAL CHARACTERISTICS

(T<sub>J</sub> = +25°C, unless otherwise noted.)

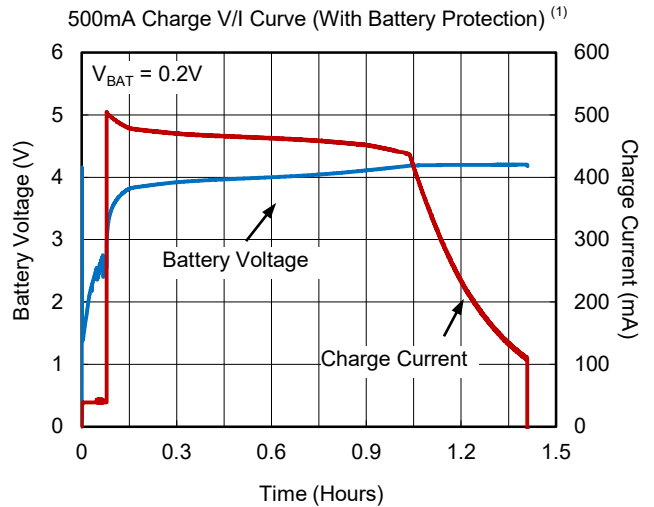
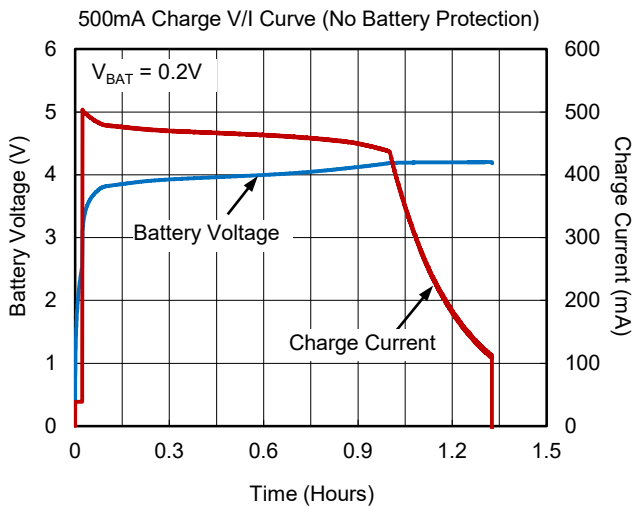
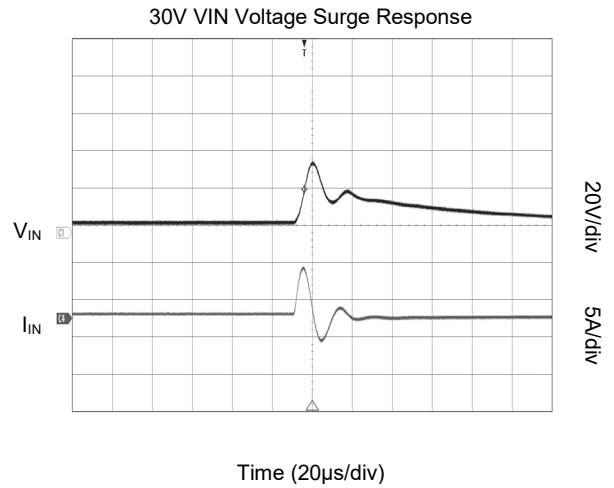
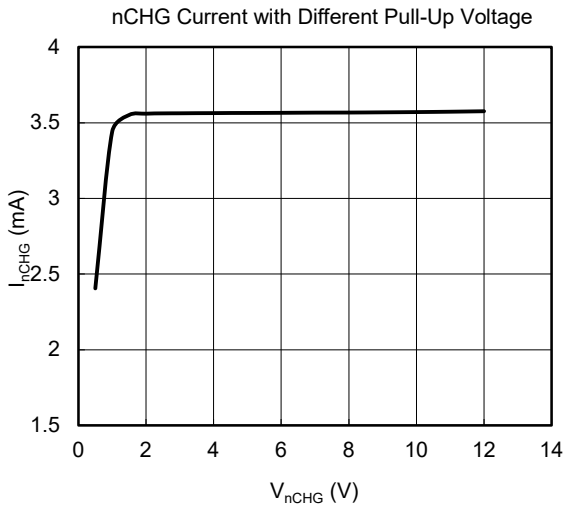
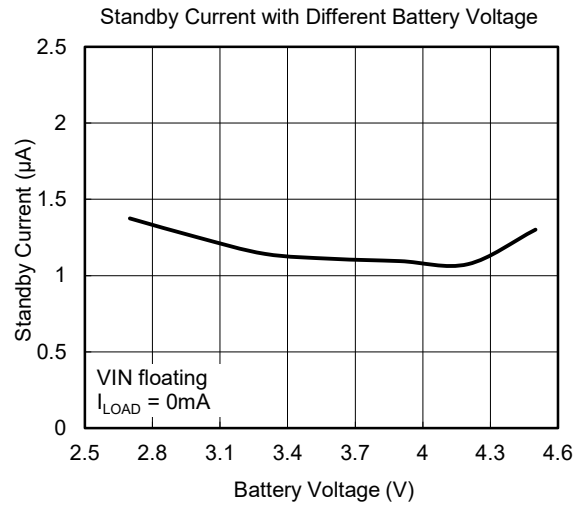
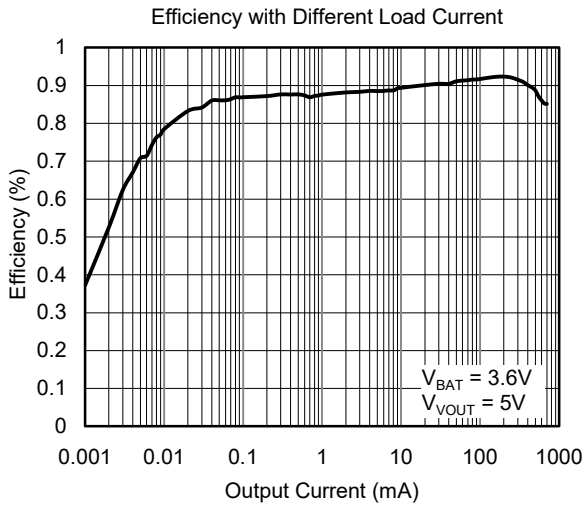
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
No Load Operation Current	I <sub>NO_OP</sub>	Test with the typical application circuit in Figure 1		70		μA
<b>Charger Only (V<sub>VIN</sub> = 5V, V<sub>BAT</sub> = 3.6V, R<sub>IREF</sub> = 120kΩ, nCHG floating.)</b>						
Operation Input Range	V <sub>OP_RANGE</sub>		2.7		7.5	V
Charge Current Range	I <sub>CH_RANGE</sub>		5		700	mA
Retaining Current	I <sub>RETAINING</sub>	Force the output voltage to 2V, R <sub>IREF</sub> = 120kΩ		200		mA
VIN-BAT Current	I <sub>FB_RANGE</sub>	V <sub>VIN</sub> - V <sub>BAT</sub> = 1V, R <sub>IREF</sub> = 13kΩ		700		mA
No Operation Current	I <sub>BAT_REVERSE</sub>	V <sub>VIN</sub> = 3V, V <sub>BAT</sub> = 5.2V, the current into BAT		9	12	μA
	I <sub>BAT_LK</sub>	V <sub>VIN</sub> = floating, V <sub>BAT</sub> = 5.2V, the current into BAT		0.08	1	μA
	I <sub>SHUT</sub>	V <sub>VIN</sub> = 6V, V <sub>IREF</sub> = 5.5V, V <sub>EN</sub> = 0V, the current into VIN		7.5	10	μA
	I <sub>NOT_CHG</sub>	V <sub>VIN</sub> = 5V, I <sub>BAT</sub> = 0mA, the current into VIN		72	110	μA
Charge Voltage	V <sub>CH</sub>	4.2V to 4.4V, 5 voltage options, in 50mV steps	4.2		4.4	V
Charge Voltage Error	V <sub>CH_ERR</sub>	I <sub>BAT</sub> = 20mA	-28		28	mV
Charge Start Voltage	V <sub>DH</sub>	V <sub>VIN</sub> - V <sub>BAT</sub> , up-going		310		mV
Reverse Block Start Voltage	V <sub>DL</sub>	V <sub>VIN</sub> - V <sub>BAT</sub> , down-going		25		mV
Charge Current at Specific R <sub>IREF</sub> Setting	I <sub>CHG</sub>	R <sub>IREF</sub> = 120kΩ	173	200	227	mA
		R <sub>IREF</sub> = 600kΩ	33.6	40	46.4	
Pre-condition Charge Voltage	V <sub>RPR</sub>	Percentage to V <sub>CH</sub>	56.5	60	64.5	%
Path Resistive Loss Compensation Voltage	V <sub>RDC</sub>	Add percentage to V <sub>CH</sub>	1.2	2	2.7	%
Drop Compensation Check Voltage	V <sub>DCC</sub>	Drop percentage to V <sub>CH</sub>	0.3	2.2	4	%
Fold-Back Voltage	V <sub>FB</sub>	Drop percentage to V <sub>CH</sub>	3.3	4	4.6	%
Floating and Recharge Voltage	V <sub>FLTING_RC</sub>	Drop percentage to V <sub>CH</sub> for floating time counting; drop percentage to V <sub>FB</sub> for recharging		1.5	3	%
End of Charge Current	I <sub>EOC</sub>	Percentage to I <sub>CHG</sub>	15	20	25	%
Pre-Condition Charge Current	I <sub>PR</sub>	Percentage to I <sub>CHG</sub>	3	7.5	14.5	%
Floating Charge Time	t <sub>FLTING</sub>			44		Min
System Load Pre-charge	t <sub>SYS_PRE</sub>			21		ms
Charge-On Sinking Time	t <sub>ON</sub>			160		ms
Charge-On Driving Cycle Time	t <sub>C</sub>			1.28		s
End of Charge Sinking Time	t <sub>EOC</sub>			51.2		s
Charge Current Regulated Temperature	T <sub>CUT</sub>			130		°C
<b>IO Characteristics for Indication Drive and Logic Control Input</b>						
Charge Disable Voltage	V <sub>TIREF</sub>				1.6	V
nCHG Low Sinking	I <sub>SNK</sub>	Pull nCHG to 5V		3.6		mA
nCHG Leakage	I <sub>LKG</sub>	Pull nCHG to 5V		0.01		μA

**ELECTRICAL CHARACTERISTICS (continued)**(T<sub>J</sub> = +25°C, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
<b>Boost Only (V<sub>BAT</sub> = 2.7V to 5.2V, C<sub>BAT</sub> = 10μF, C<sub>VOUT</sub> = 20μF, typical values are at V<sub>BAT</sub> = 3.7V.)</b>						
Output Voltage	V <sub>OUT_PWM</sub>	V <sub>BAT</sub> < V <sub>VOUT</sub> , in PWM mode operation	4.84	5.00	5.09	V
	V <sub>OUT_PFM</sub>	V <sub>BAT</sub> < V <sub>VOUT</sub> , in PFM mode operation		5.04		
Output Current	I <sub>OUT_RANGE</sub>			500		mA
Quiescent Current into BAT Pin	I <sub>Q</sub>	No load, not switching		0.08	0.6	μA
Quiescent Current into VOUT Pin		No load, not switching, boost or down mode		0.6	1	μA
Peak Current Limit	I <sub>LIM</sub>	boost operation	0.89	1.3	1.62	A
Switch Frequency	f <sub>SW</sub>	V <sub>BAT</sub> = 3.7V	0.98	1.2	1.35	MHz
Low-side Switch On-Resistance	R <sub>ON_L</sub>			300	420	mΩ
High-side Switch On-Resistance	R <sub>ON_H</sub>			320	410	mΩ
Boost Stop Temperature	T <sub>OT</sub>	The temperature boost stops		150		°C
Resuming Temperature	T <sub>HYS</sub>	Temperature drop for boost resuming operation		25		°C
<b>Control Logic</b>						
EN High Threshold	V <sub>IH</sub>		1.20			V
EN Low Threshold	V <sub>IL</sub>				0.40	V
EN Input Leakage	I <sub>EN_LKG</sub>	V <sub>BAT</sub> = V <sub>EN</sub> = 5V			0.3	μA

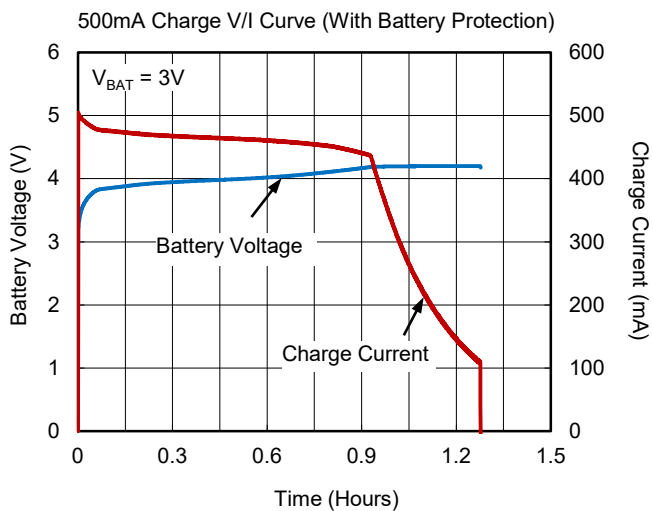
TYPICAL PERFORMANCE CHARACTERISTICS

T<sub>J</sub> = +25°C, V<sub>VIN</sub> = 5V, EN = V<sub>BAT</sub>, V<sub>BAT</sub> = 3.6V, unless otherwise noted.



**TYPICAL PERFORMANCE CHARACTERISTICS (continued)**

T<sub>J</sub> = +25°C, V<sub>VIN</sub> = 5V, EN = V<sub>BAT</sub>, V<sub>BAT</sub> = 3.6V, unless otherwise noted.



NOTE:

1. The plot is acquired in test with a battery pack with the SGM41100 series battery protector. Voltage profile in range < 2.5V reflects the protector behavior, and the current profile droop is path resistance dependent.

FUNCTIONAL BLOCK DIAGRAM

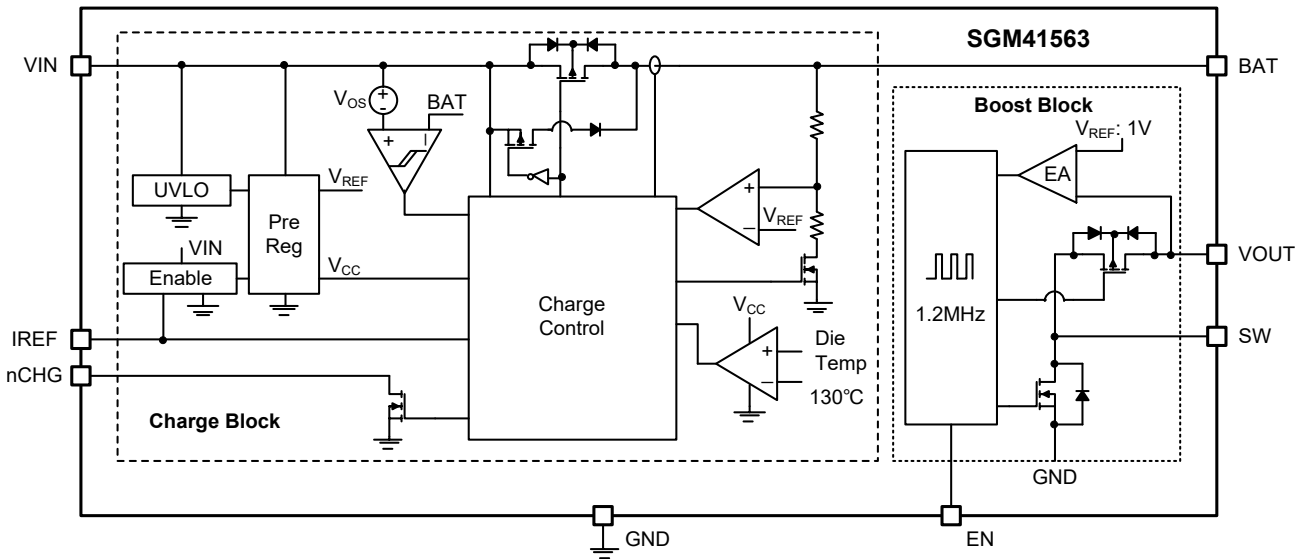


Figure 2. Block Diagram

ESSENTIAL SEQUENCE

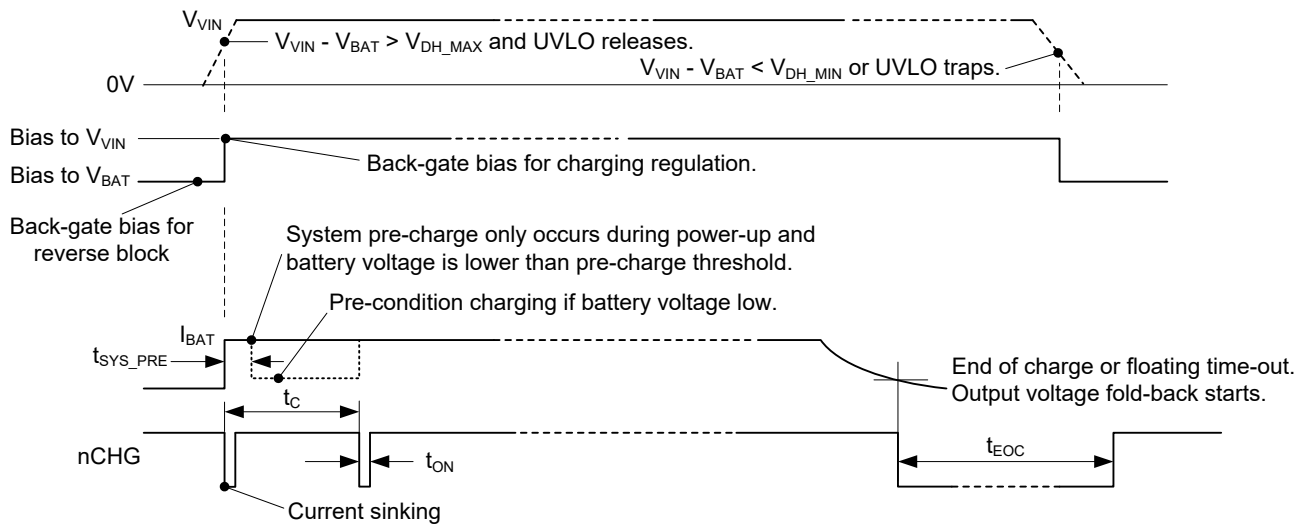


Figure 3. Essential On/Off Timing



## DETAILED DESCRIPTION

The SGM41563 has a linear battery charger block with low I<sub>Q</sub> boost operation which is biased from the BAT pin. It only consumes ultra-low quiescent current less than 1μA, which is designed for the always-on standby applications.

### The Linear Charger

The charger block uses a CC/CV charge profile, plus the following added features for improving safety, suitability and availability:

**System Load Pre-charge:** When power up in the situation that the battery terminal voltage is below the pre-condition voltage threshold, the output with maximum current limit for t<sub>SYS\_PRE</sub> to provide enough current for the system to start up with no battery or with a battery in under-voltage protection state.

**Wide Available Input Range:** Charging is kept when the input voltage is high or when the supply could not maintain enough voltage and current. The charge current is regulated for no over-heating the device or maintains minimum drop-out for no reverse leakage, even the current could not be maintained continuously.

**Voltage Fold-Back Power Retaining:** When EOC condition is qualified, lower the output to a safe voltage while release the current limit to the maximum, retain powering the load system. The fold-back does not sink charge back out of the battery and avoids discharging and recharging cycling in continuous plugged-in situation.

**Floating Charge Time-Out:** When charging with high system load that sinks more than the end of charge residual current, charging stops when the battery voltage stays higher than floating charge voltage for over t<sub>FLTING</sub> and turns in the end of charge fold-back power retaining.

**Over-Temperature Charge Regulation:** The device senses temperature with its on-die sensing circuit. When the die temperature reaches T<sub>CUT</sub>, the charge current is reduced for maintaining the temperature.

**Path Resistive Loss Compensation and Charge Termination Current:** Once the end of charge condition is detected the first time, the charge is turned to output V<sub>FB</sub> while the V<sub>BAT</sub> is checked; a drop is seen as the current in the charge path falls. If the drop is significant, more than V<sub>DCC</sub>, the output voltage is then increased to V<sub>RDC</sub> to compensate as the excessive loss drop detected. This allows using relative high residual

current level for charge termination detection while the bigger portion of charge current goes into load instead of into current.

**Charging Procedure, Start, End of Charge, Power Retaining and Restart:** There are two kinds of charge procedure, charging a battery cell without any battery protector and with a battery protector. The devices' native charging procedure is recorded with a battery without any protector, in which the system pre-charge, battery pre-charge, floating, end of charge and safe fold-back power retaining are included. When charging a battery with a protector, the start-end curve is affected by the protector's behavior and the residual battery voltage is kept by the protector, in which the BAT voltage raises too fast that no much difference to chargers with a battery FET.

The charge procedure is provided as a constant current and constant voltage, with a system pre-charge at power up and a pre-condition charging if the battery voltage is lower than the fast charging threshold. The end of charge is qualified when the charge current falls to the termination current in the floating charge period or floating timer runs out of time, once or after the path resistive loss compensated. Charge procedure parameters are illustrated in Figure 3 as well, in which timing is not scaled for showing details in short time intervals.

**Charge Current Programming:** The current passing through the VIN to BAT path is sampled and the current is proportional to the path current that is fed out of the IREF pin. The proportional current goes through the R<sub>IREF</sub> and makes a voltage drop over the R<sub>IREF</sub> proportional to the path current. The current regulation loop controls the path resistance to make the drop equal to an internal reference voltage unless the voltage regulation loop takes control. The current sample ratio, R<sub>IREF</sub> and the internal reference voltage decide the path current when the current loop takes control. The relationship between the R<sub>IREF</sub> and the path current is represented as:

$$I_{CHG} = 24000/R_{IREF} \text{ (k}\Omega\text{) for } I_{CHG} < 400\text{mA}$$

$$I_{CHG} = 58\text{(mA)} + 20500/R_{IREF} \text{ (k}\Omega\text{) for } I_{CHG} > 400\text{mA}$$

DETAILED DESCRIPTION (continued)

The Boost Converter

The boost block operates in peak-current PWM mode in normal load condition, and turns into power-saving skip mode in light load condition. The power input to load is disconnected when it is disabled by pulling EN low.

In addition to the normal regulation, both the peak inductor current and the output voltage are monitored for over-current protection and short circuit protection. Whenever the peak current reaches I<sub>LIM</sub>, the low-side switch is turned off. Whenever the output voltage falls below 2.2V, the output is pre-charged through the high-side switch that has a current limit for about 200mA. The switching operation stops whenever the output voltage is higher than the over-voltage protection threshold (V<sub>OV</sub>), or the die temperature is higher than the over-temperature threshold (T<sub>OT</sub>).

Careful Handling to In-Rush and Out-Rush: In-rush voltage surge or out-rush voltage surge might occur and damage the low voltage pins BAT and VOUT during the battery attaching or the supply applying in production test in the always-on circuit showed in Figure 4.

It is recommended to place TVS diodes clipping to the BAT pin and VOUT pin for surge absorption. However, if you decide not to use TVS diodes, the R1 and C6 are alternatives in the always-on application, which inserts a short delay to EN enabling after battery attaching or test supply contact, to avoid the boost starting during the voltage surge. The larger capacitances of C4 and C5, as shown in Figure 4, are recommended to lowering the out-rush voltage surge caused by load contact bouncing, which is usual situation in frequent load assertion applications like TWS case, where the load contact capacitance should be less than 1/10 of the total capacitances of the C4 and C5 practically.

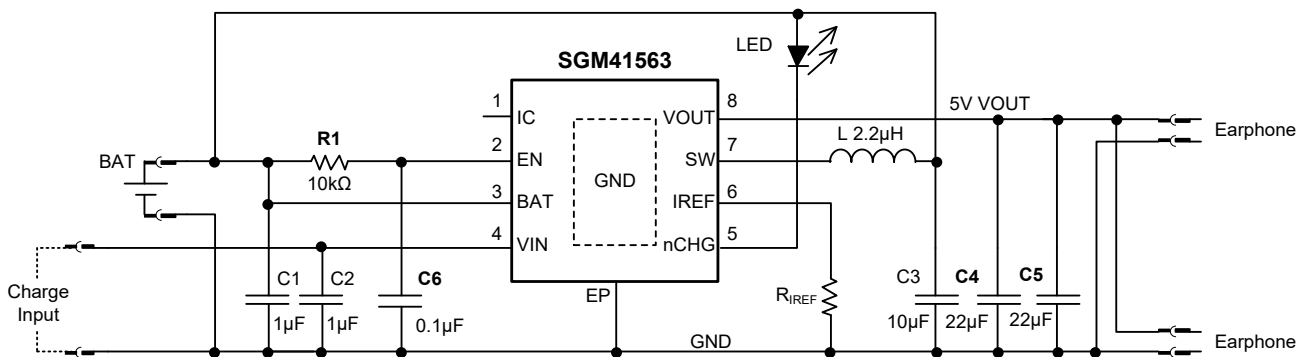


Figure 4. Typical Application Circuit for Always-on Boost in TWS Charger Case

APPLICATION INFORMATION

The typical application circuit with the recommended component parameters is shown in Figure 1. The boost keeps stable if reducing the input decoupling capacitance and the output storage capacitance to half value if not care about the increasing of the output voltage ripple amplitude and the input current ripple amplitude.

**Inductor Selection:** The low DCR inductor of 2.2μH with the saturation current and the thermal limited current > 1.4A is recommended.

**Layout Consideration:** The inductor current alternates between the ground EP and the output storage capacitors C4 - C5, while the input decoupling capacitor C3 makes the return loop of the inductor current ripple. Refer to Figure 5; it makes the ripple current loop as small as possible for stable and low loss operation.

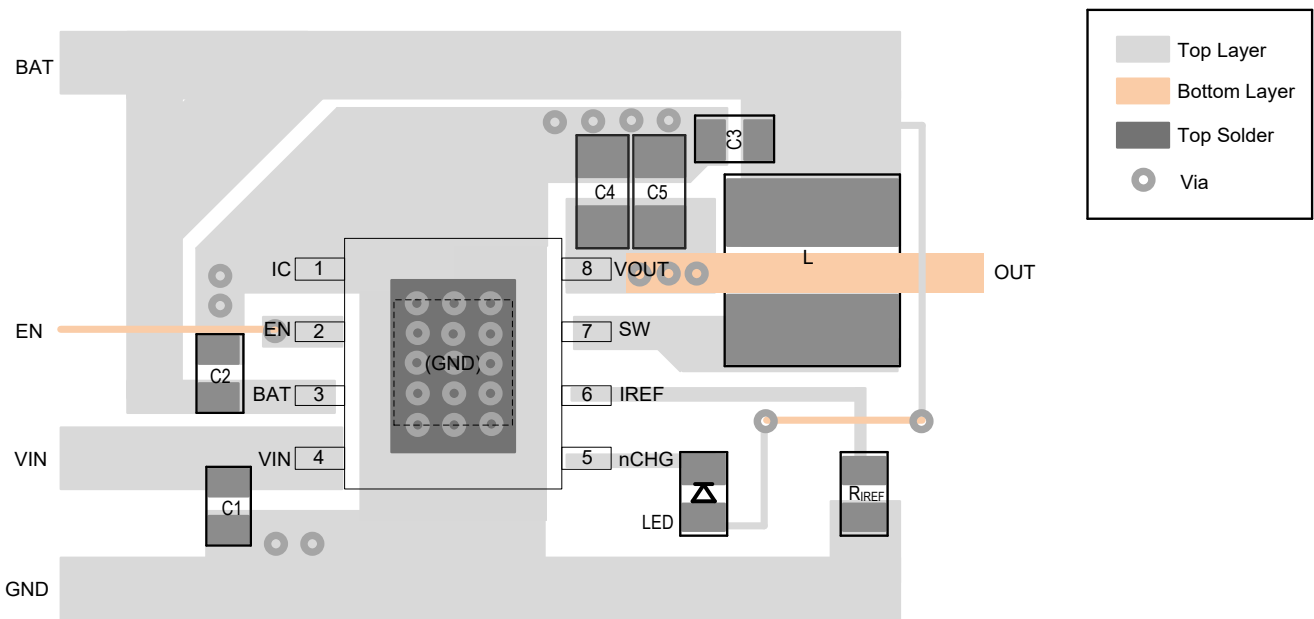


Figure 5. Layout Recommendation

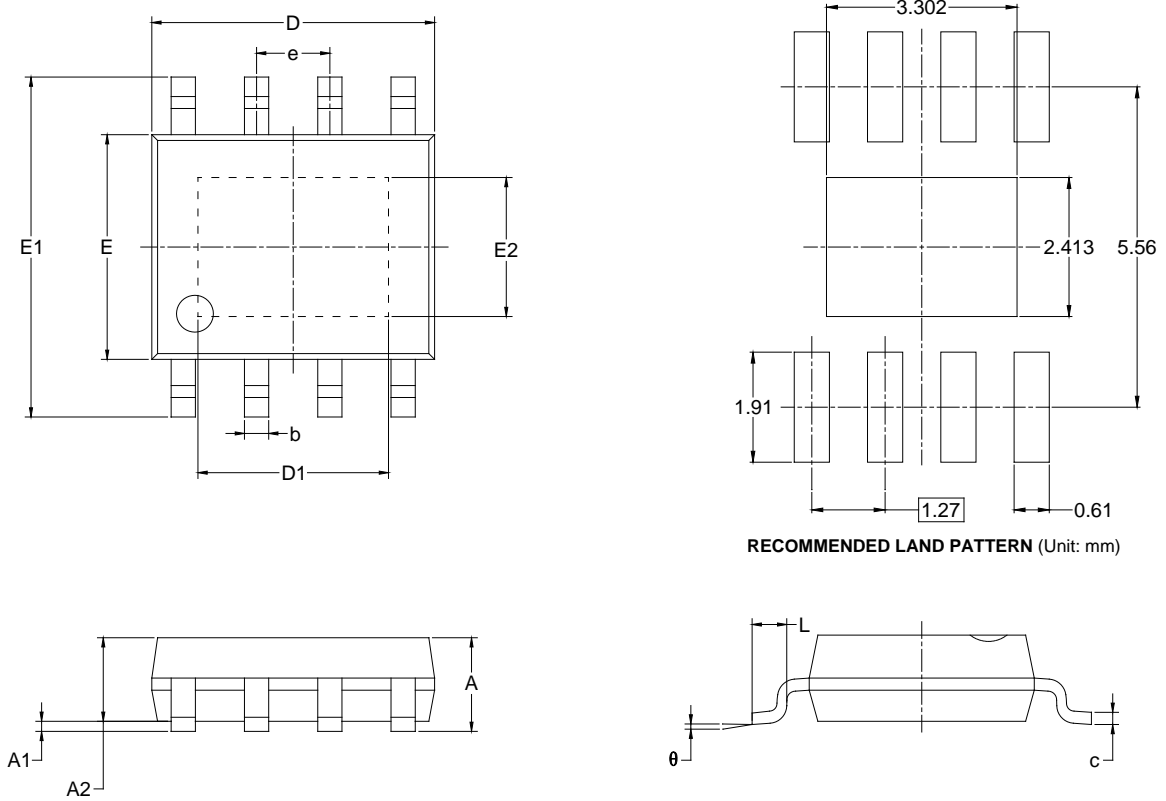
REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Original (MARCH 2020) to REV.A	Page
Changed from product preview to production data.....	All

PACKAGE OUTLINE DIMENSIONS

SOIC-8 (Exposed Pad)



RECOMMENDED LAND PATTERN (Unit: mm)

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A		1.700		0.067
A1	0.000	0.100	0.000	0.004
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.700	5.100	0.185	0.201
D1	3.202	3.402	0.126	0.134
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
E2	2.313	2.513	0.091	0.099
e	1.27 BSC		0.050 BSC	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

# PACKAGE INFORMATION

## TAPE AND REEL INFORMATION

### REEL DIMENSIONS



### TAPE DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

### KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
SOIC-8 (Exposed Pad)	13"	12.4	6.40	5.40	2.10	4.0	8.0	2.0	12.0	Q1

000001

# PACKAGE INFORMATION

## CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

## KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
13"	386	280	370	5

DD0002